

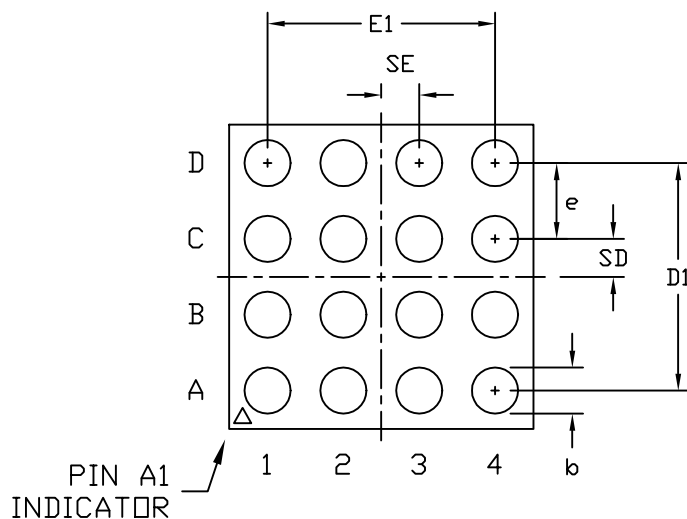
TOP VIEW

COMMON DIMENSIONS	
A	0.62+0.05-0.08
A1	0.29±0.02
A2	0.33 REF.
b	∅0.35±0.03
D1	1.50 BASIC
E1	1.50 BASIC
e	0.50 BASIC
SD	0.25 BASIC
SE	0.25 BASIC

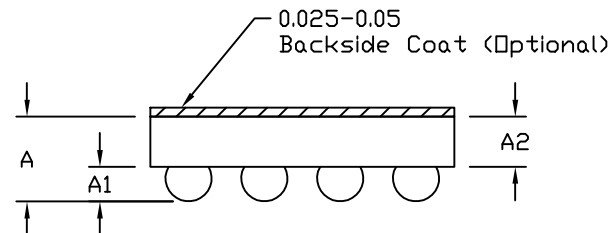
PKG. CODE	VARIABLE DIMENSIONS		DEPOPULATED SOLDER BALLS
	D	E	
B16-1	2.02±0.05	2.02±0.05	NONE
B16-2	2.02±0.05	2.02±0.05	B3, C3
B16-3	2.02±0.05	2.02±0.05	B3, C2
B16-4	2.02±0.05	2.02±0.05	B2, C3
B16-5	2.02±0.05	2.02±0.05	B2, B3, C2, C3
B16-6	2.02±0.05	2.02±0.05	C3

NOTES:

1. All dimensions in millimeters.
2. Outer dimension (D & E) is defined by center lines between scribe lines.
3. Marking shown is for package orientation reference only. Number of characters and lines vary per product.
4. All dimensions are applicable to Leaded (-), PbFree (+), and MaxFilm parts/pkg codes.



BOTTOM VIEW



SIDE VIEW

-DRAWING NOT TO SCALE-

MAXIM			
TITLE: PACKAGE OUTLINE, 16 BUMPS, 4X4 ARRAY, UCSP (B) PKG.			
APPROVAL TIE WANG 09/09/09	DOCUMENT CONTROL NO. 21-0101	REV. I	1/1